



**SDI Review Form 1.6**

Journal Name:	<a href="#">Journal of Engineering Research and Reports</a>
Manuscript Number:	Ms_JERR_46080
Title of the Manuscript:	Challenges and Resolution for Copper Wirebonding on Tapeless Leadframe Chip-On-Lead Technology
Type of the Article	Original Research Article

**General guideline for Peer Review process:**

This journal's peer review policy states that **NO** manuscript should be rejected only on the basis of '**lack of Novelty**', provided the manuscript is scientifically robust and technically sound. To know the complete guideline for Peer Review process, reviewers are requested to visit this link:

(<http://www.sciencedomain.org/page.php?id=sdi-general-editorial-policy#Peer-Review-Guideline>)

**PART 1: Review Comments**

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
<b>Compulsory</b> REVISION comments	Nil	
<b>Minor</b> REVISION comments	Line 378: "CONCLUSIONS AND RECOMMENDATIONS" <i>should read</i> "CONCLUSION AND RECOMMENDATIONS"	
<b>Optional/General</b> comments	Nil	

**PART 2:**

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
Are there ethical issues in this manuscript?	(If yes, Kindly please write down the ethical issues here in details)	

**Reviewer Details:**

Name:	<b>Hachimenum Nyebuchi Amadi</b>
Department, University & Country	<b>Federal University of Technology, Nigeria</b>